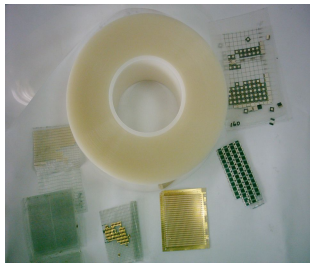


UV TAPE

PanTech UV tape, also called as **UV off tape** is an adhesive tape specially designed for dicing of **wafer, LED module, QFN, glass IC chips, and package sawing singulations**. It sustains a strong adhesion and turns to very low adhesion after UV exposure. This tape can hold the chips firmly during dicing, and chips can be picked up or peeled off easily after UV exposure.

These are all [RoHS](#) and [halogen free](#).



Dicing Tape for PCB



Wafer Dicing Tape



Dicing tape for glass

Usage/base film	Adhesion	130μPO	80μPO	140μPO	80μPO	100μPET
QFN Dicing PCB Dicing	Ultra high	UP163-H24 UP163	—			UT1005
Glass Dicing Ceramic Dicing	Strong	UP163-20 UP151	UP821	UB163-20 UB151		
Wafer Dicing	low	—	UP802 UP804		UB802	
Expandable/ recovery		No	No	Yes	Yes	No
color		matt	matt	matt	matt	Clear
Advantage		clean removal	clean removal	Expandable	Expandable	excellent Temp. R. Stiffness
Disadvantage						Stiffness